

Title (en)

OPTICAL INTERCONNECTION SYSTEM IN A MICROELECTRONIC CIRCUIT PRODUCED ON A SOI SUBSTRATE

Title (de)

OPTISCHE VERBINDUNGSSYSTEM IN EINER AUF EINEM SOI SUBSTRAT HERGESTELLTEN MIKROELEKTRONISCHEN SCHALTUNG

Title (fr)

SYSTEME D'INTERCONNEXION OPTIQUE DANS UN CIRCUIT MICROELECTRONIQUE REALISE SUR UN SUBSTRAT SOI

Publication

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Application

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Abstract (en)

[origin: WO0210816A2] The invention concerns an optical interconnection system in a microelectronic circuit produced on a SOI substrate (30), that is a substrate having a silicon film (33) supported by an electrically insulating material (32), the microelectronic circuit comprising at least a functional block to be connected produced in the silicon film. The system comprises at least an optical microguide consisting of a strip (40) delimited in the silicon film by lateral confinement zones (41, 42) to connect the functional block.

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